

ABSTRACT**PROCESS FOR TRANSFERRING A SUPERFICIAL LAYER TO CAVITIES**

The invention relates to a process for transferring a superficial layer (10) to a carrier substrate (20) containing cavities (23), the process comprising:

- providing a donor substrate,
- providing the carrier substrate (20), the latter having a first side and containing cavities (23), each cavity opening onto said first side and having a bottom and peripheral walls,
- producing at least one temporary pillar (30) in at least one of the cavities (23), the pillar (30) having an upper surface that is coplanar with the first side of the carrier substrate (20),
- joining the donor substrate and the carrier substrate (20) via the first side of the carrier substrate,
- thinning the donor substrate, so as to form the superficial layer (10),
- removing the at least one temporary pillar (30).

Fig. 2I